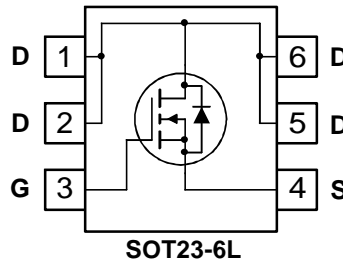


**Features**

- 2.6 A, 100 V  $R_{DS(ON)} = 90\text{ m}\Omega @ V_{GS} = 10\text{ V}$   
 $R_{DS(ON)} = 85\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
- High performance trench technology for extremely low  $R_{DS(ON)}$
- Low gate charge (14nC typ)
- High power and current handling capability
- Fast switching speed

**Applications**

- DC/DC converter

**Pin Configuration**

**SOT23-6L**
**Absolute Maximum Ratings**  $T_A=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain-Source Voltage	100	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous (Note 1a)	2.6	A
	– Pulsed	20	
$P_D$	Maximum Power Dissipation (Note 1a) (Note 1b)	1.6	W
		0.8	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +125	$^\circ\text{C}$

**Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	78	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	30	$^\circ\text{C/W}$

**Package Marking and Ordering Information**

Device Marking	Device	Reel Size	Tape width	Quantity
JY10220	JY10220	7"	8mm	3000 units

<b>Electrical Characteristics</b>		$T_A = 25^\circ\text{C}$ unless otherwise noted				
<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>	<b>Units</b>
<b>Drain-Source Avalanche Ratings (Note 2)</b>						
$W_{DSS}$	Drain-Source Avalanche Energy	Single Pulse, $V_{DD} = 50\text{ V}$ , $I_D = 2.6\text{ A}$			90	mJ
$I_{AR}$	Drain-Source Avalanche Current				2.6	A
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , Referenced to $25^\circ\text{C}$		99		mV/°C
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 80\text{ V}$ , $V_{GS} = 0\text{ V}$			10	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage, Forward	$V_{GS} = 20\text{ V}$ , $V_{DS} = 0\text{ V}$			100	nA
$I_{GSSR}$	Gate-Body Leakage, Reverse	$V_{GS} = -20\text{ V}$ , $V_{DS} = 0\text{ V}$			-100	nA
<b>On Characteristics (Note 2)</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	1	2.3	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , Referenced to $25^\circ\text{C}$		-6		mV/°C
$R_{DS(on)}$	Static Drain-Source On Resistance	$V_{GS} = 10\text{ V}$ , $I_D = 1\text{ A}$ $V_{GS} = 4.5\text{ V}$ , $I_D = 1\text{ A}$		85 90	110 125	m $\Omega$
$I_{D(on)}$	On-State Drain Current	$V_{GS} = 10\text{ V}$ , $V_{DS} = 5\text{ V}$	10			A
$g_{FS}$	Forward Transconductance	$V_{DS} = 10\text{ V}$ , $I_D = 2.6\text{ A}$		10		S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 50\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1.0\text{ MHz}$		660		pF
$C_{oss}$	Output Capacitance			55		pF
$C_{rss}$	Reverse Transfer Capacitance			40		pF
<b>Switching Characteristics (Note 2)</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 50\text{ V}$ , $I_D = 1\text{ A}$ , $V_{GS} = 10\text{ V}$ , $R_{GEN} = 6\text{ }\Omega$		6	11	ns
$t_r$	Turn-On Rise Time			3.5	7	ns
$t_{d(off)}$	Turn-Off Delay Time			23	37	ns
$t_f$	Turn-Off Fall Time			3.7	7.4	ns
$Q_g$	Total Gate Charge	$V_{DS} = 50\text{ V}$ , $I_D = 2.6\text{ A}$ , $V_{GS} = 10\text{ V}$		14	20	nC
$Q_{gs}$	Gate-Source Charge			2.3		nC
$Q_{gd}$	Gate-Drain Charge			3.6		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain-Source Diode Forward Current				1.3	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}$ , $I_S = 1.3\text{ A}$ (Note 2)		0.76	1.2	V
$t_{rr}$	Diode Reverse Recovery Time	$I_F = 2.6\text{ A}$		31		nS
$Q_{rr}$	Diode Reverse Recovery Charge	$d_{IF}/d_t = 100\text{ A}/\mu\text{s}$ (Note 2)		56		nC

**Notes:**

- $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.
  - $78^\circ\text{C/W}$  when mounted on a  $1\text{ in}^2$  pad of 2oz copper on FR-4 board.
  - $156^\circ\text{C/W}$  when mounted on a minimum pad.
- Pulse Test: Pulse Width  $\leq 300\text{ }\mu\text{s}$ , Duty Cycle



### Typical Characteristics

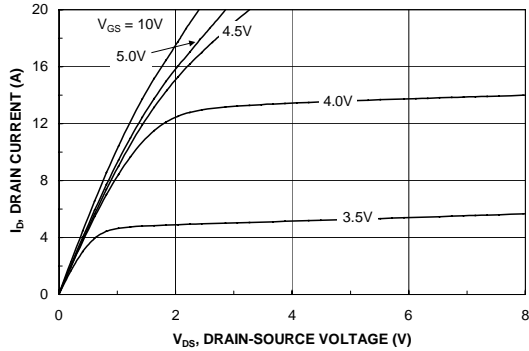


Figure 1. On-Region Characteristics.

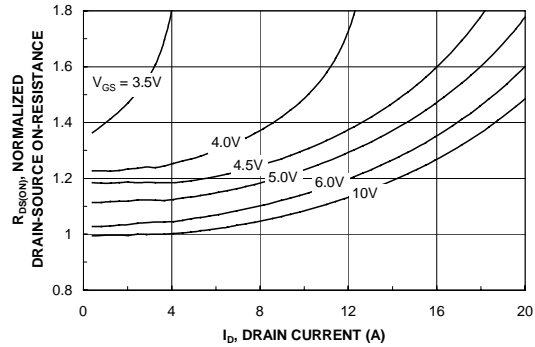


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

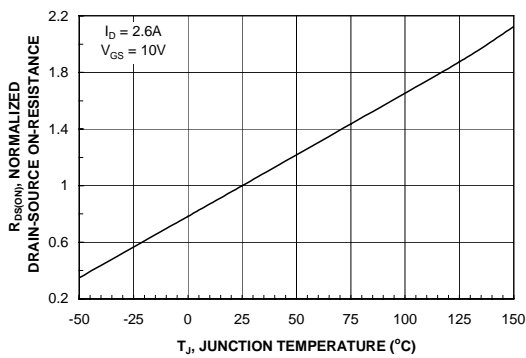


Figure 3. On-Resistance Variation with Temperature.

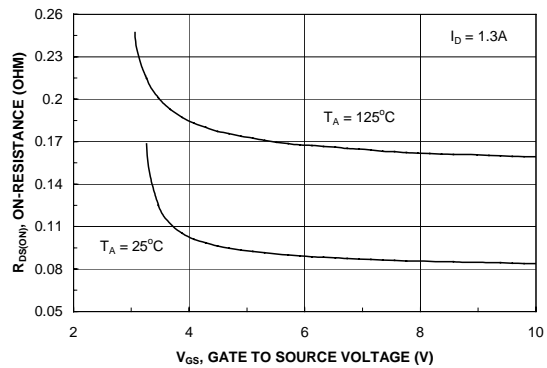


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

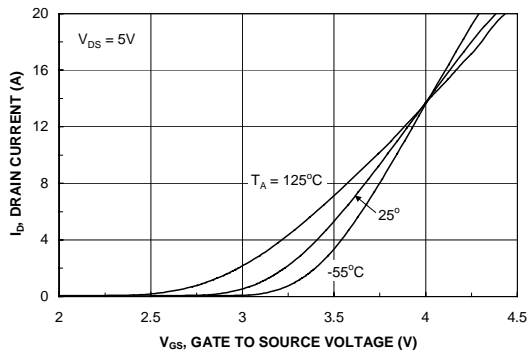


Figure 5. Transfer Characteristics.

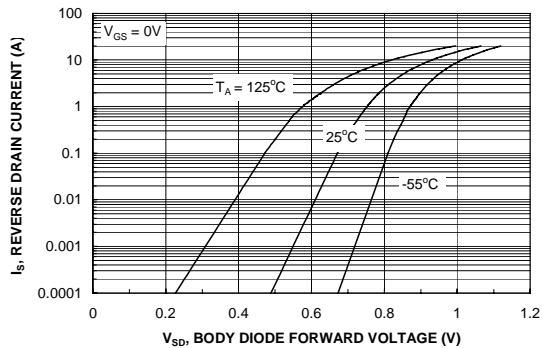
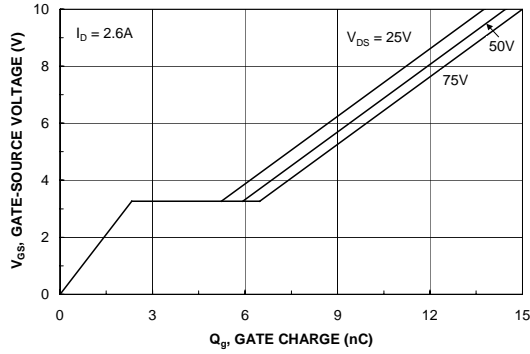
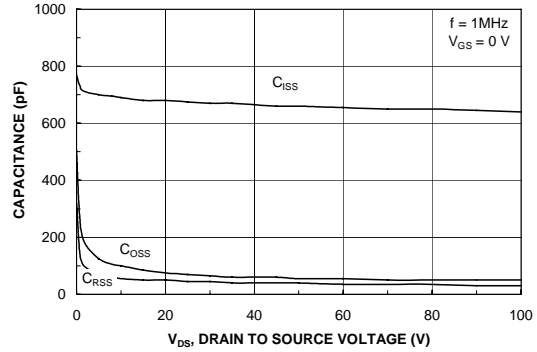


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

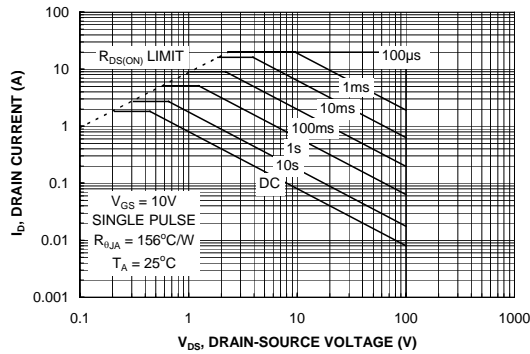
**Typical Characteristics**



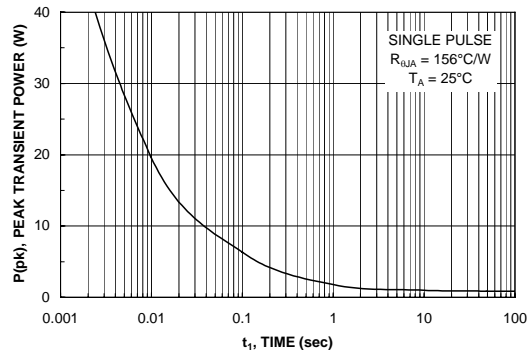
**Figure 7. Gate Charge Characteristics.**



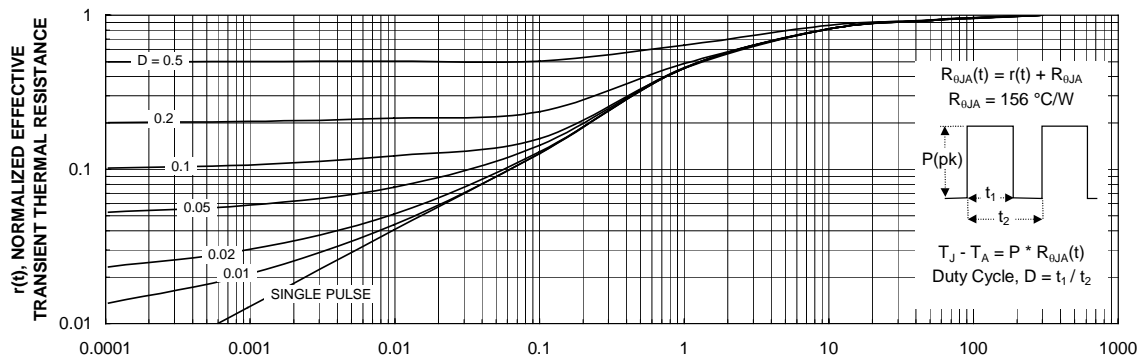
**Figure 8. Capacitance Characteristics.**



**Figure 9. Maximum Safe Operating Area.**



**Figure 10. Single Pulse Maximum Power Dissipation.**



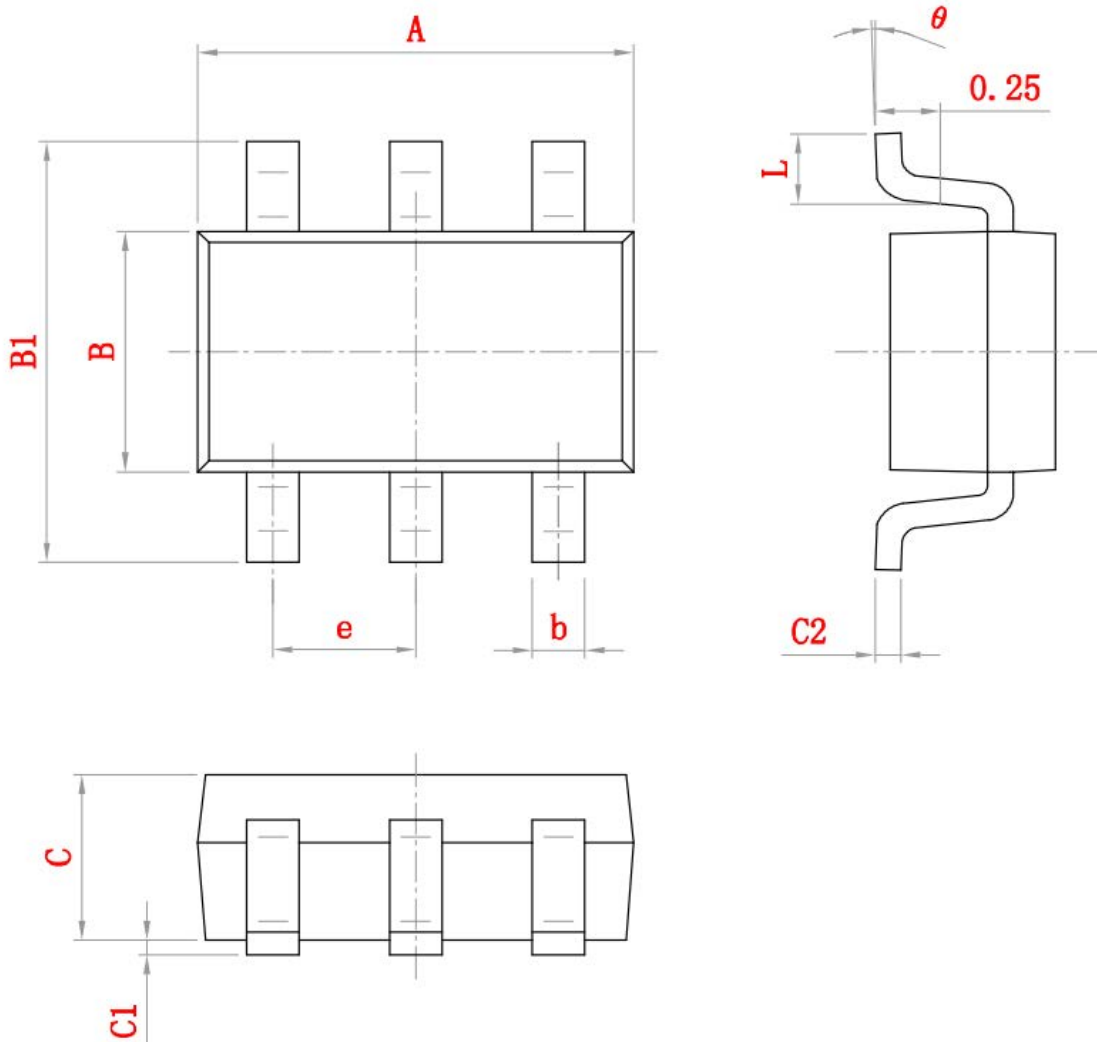
**Figure 11. Transient Thermal Response Curve.**

Thermal characterization performed using the conditions described in Note 1b.  
Transient thermal response will change depending on the circuit board design.

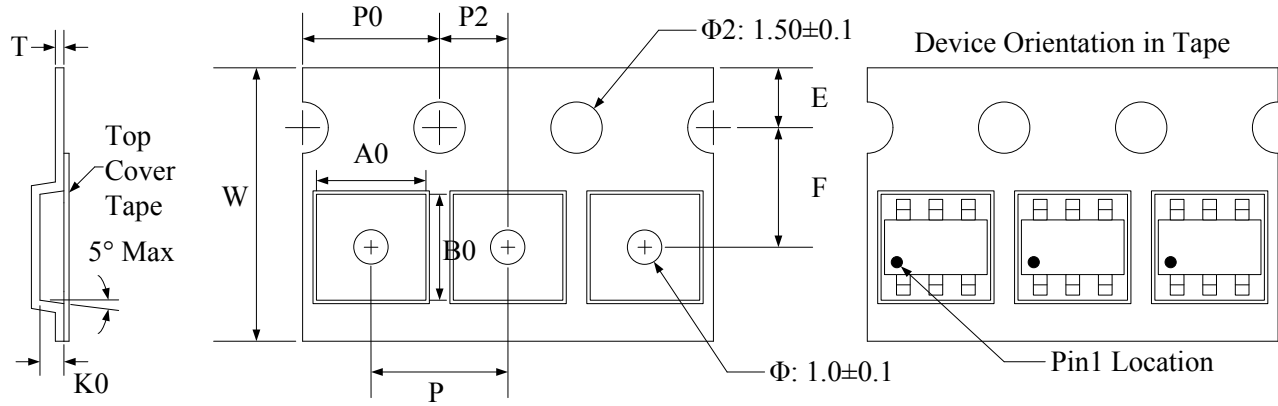
**Package Outline**

□ SOT23-6L package

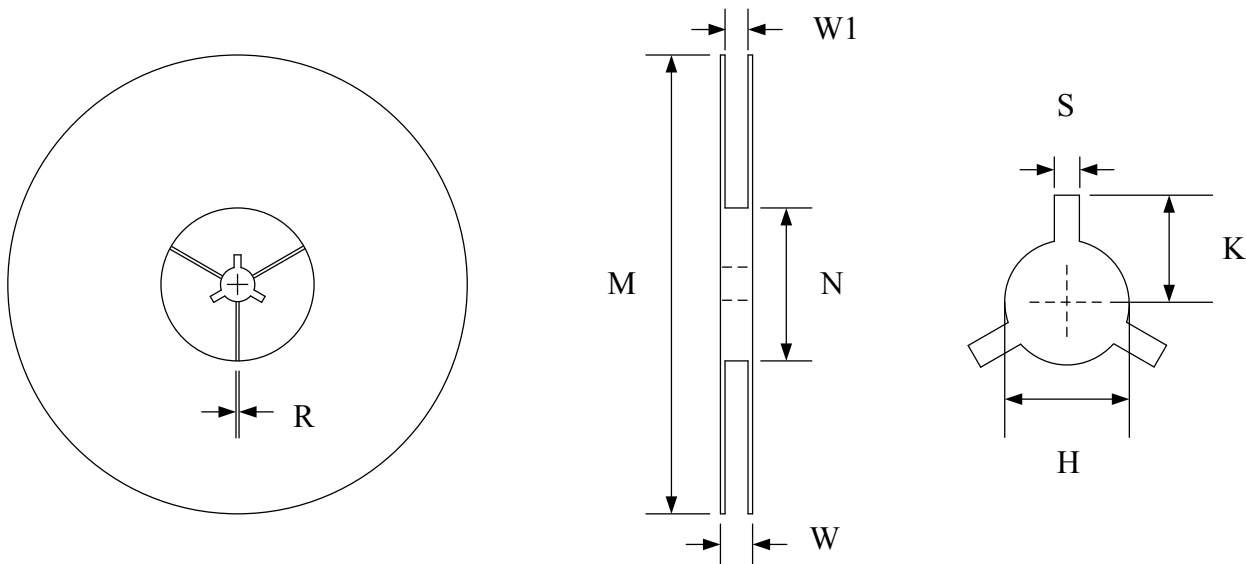
尺寸 标注	最小 (mm)	最大 (mm)	尺寸 标注	最小 (mm)	最大 (mm)
A	2.82	3.02	C	1.05	1.15
e	0.95 (BSC)		C1	0.03	0.15
b	0.28	0.45	C2	0.12	0.23
B	1.50	1.70	L	0.35	0.55
B1	2.60	3.00	$\theta$	0°	8°



### Tape and Reel Specification

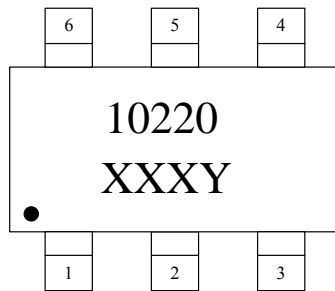


Symbol	W	A0	B0	K0	E	F	P	P0	P2	T
Dimensions (mm)	$8.00 \pm 0.3$ $-0.1$	$3.23 \pm 0.05$	$3.17 \pm 0.05$	$1.37 \pm 0.05$	$1.75 \pm 0.1$	$3.5 \pm 0.05$	$4.0 \pm 0.1$	$4.0 \pm 0.1$	$2.0 \pm 0.05$	$0.25 \pm 0.02$



Symbol	Reel Size	M	N	W	W1	H	S	K	R
Dimensions (mm)	$\Phi 178$	$178.0 \pm 1.0$	$60.0 \pm 1.0$	$11.5 \pm 0.5$	$9.0 \pm 0.5$	$13.0 \pm 0.5$	$2.0 \pm 0.1$	$11.0 \pm 0.2$	$1.0 \pm 0.05$

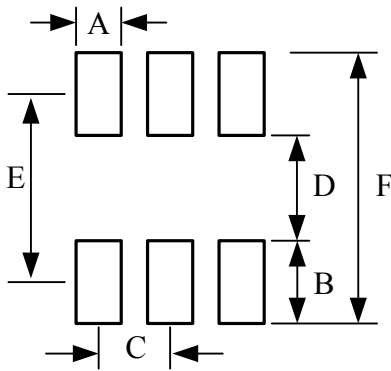
### Marking Codes



**Note:**

- (1) “10220” is the part number, fixed.
- (2) “XXX” is the last 3 characters of the wafer's Lot No.,  
“Y” is the internal code.

### Footprint: SOT23-6L



Symbol	Dimensions	
	Millimeters	Inches
A	0.60	0.024
B	1.10	0.043
C	0.95	0.037
D	1.40	0.055
E	2.50	0.098
F	3.60	0.141

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